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Kind regards,

Team Nexperia

74AHC125; 74AHCT125

Quad buffer/line driver; 3-state

Rev. 04 — 11 January 2008

Product data sheet

1. General description

The 74AHC125; 74AHCT125 is a high-speed Si-gate CMOS device and is pin compatible with Low-power Schottky TTL (LSTTL). They are specified in compliance with JEDEC standard JESD7-A.

The 74AHC125; 74AHCT125 provides four non-inverting buffer/line drivers with 3-state outputs. The 3-state outputs (nY) are controlled by the output enable input ($\overline{\text{NOE}}$). A HIGH at $\overline{\text{NOE}}$ causes the outputs to assume a high-impedance OFF-state.

The 74AHC125; 74AHCT125 is identical to the 74AHC126; 74AHCT126 but has active LOW enable inputs.

2. Features

- Balanced propagation delays
- All inputs have a Schmitt-trigger action
- Inputs accepts voltages higher than V_{CC}
- For 74AHC125 only: operates with CMOS input levels
- For 74AHCT125 only: operates with TTL input levels
- ESD protection:
 - ◆ HBM JESD22-A114E exceeds 2000 V
 - MM JESD22-A115-A exceeds 200 V
 - ◆ CDM JESD22-C101C exceeds 1000 V
- Multiple package options
- Specified from -40 °C to +85 °C and from -40 °C to +125 °C

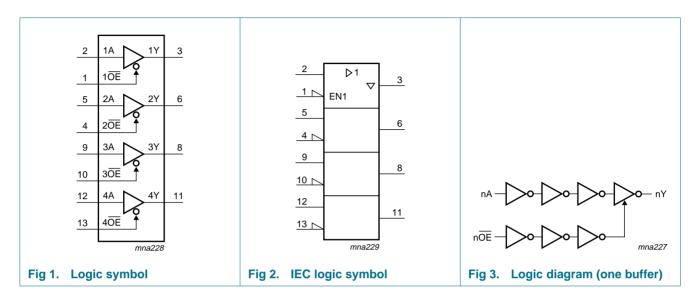
3. Ordering information

Table 1. Ordering information

Type number	Package									
	Temperature range	Name	Description	Version						
74AHC125D	–40 °C to +125 °C	SO14	plastic small outline package; 14 leads;	SOT108-1						
74AHCT125D			body width 3.9 mm							
74AHC125PW	–40 °C to +125 °C	TSSOP14	plastic thin shrink small outline package; 14 leads;	SOT402-1						
74AHCT125PW			body width 4.4 mm							
74AHC125BQ	–40 °C to +125 °C	DHVQFN14	1	SOT762-1						
74AHCT125BQ			thin quad flat package; no leads; 14 terminals; body $2.5 \times 3 \times 0.85$ mm							

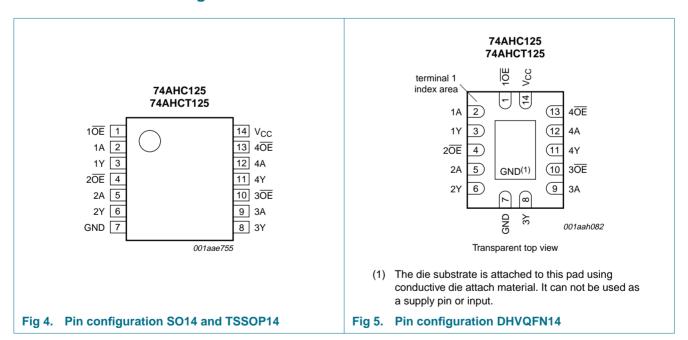


4. Functional diagram



5. Pinning information

5.1 Pinning



5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1 OE	1	output enable input (active LOW)
1A	2	data input
1Y	3	data output
2 OE	4	output enable input (active LOW)
2A	5	data input
2Y	6	data output
GND	7	ground (0 V)
3Y	8	data output
3A	9	data input
3 OE	10	output enable input (active LOW)
4Y	11	data output
4A	12	data input
4 OE	13	output enable input (active LOW)
V_{CC}	14	supply voltage

6. Functional description

Table 3. Function table[1]

Control	Input	Output
nOE	nA	nY
L	L	L
	Н	Н
Н	X	Z

^[1] H = HIGH voltage level;

L = LOW voltage level;

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+7.0	V
VI	input voltage		-0.5	+7.0	V
I _{IK}	input clamping current	$V_1 < -0.5 V$	[1] -20	-	mA
l _{OK}	output clamping current	$V_O < -0.5 \text{ V or } V_O > V_{CC} + 0.5 \text{ V}$	<u>[1]</u> _	±20	mA
lo	output current	$V_{O} = -0.5 \text{ V to } (V_{CC} + 0.5 \text{ V})$	-	±25	mA
I _{CC}	supply current		-	75	mA
I _{GND}	ground current		-75	-	mA

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X = don't care;

Z = high-impedance OFF-state.

Table 4. Limiting values ...continued

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
T_{stg}	storage temperature		-65	+150	°C
P _{tot}	total power dissipation	$T_{amb} = -40 ^{\circ}\text{C} \text{ to } +125 ^{\circ}\text{C}$			
	SO14 package		[2] -	500	mW
	TSSOP14 package		<u>[3]</u> _	500	mW
	DHVQFN14 package		<u>[4]</u> _	500	mW

- [1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
- [2] Ptot derates linearly with 8 mW/K above 70 °C.
- [3] Ptot derates linearly with 5.5 mW/K above 60 °C.
- [4] Ptot derates linearly with 4.5 mW/K above 60 °C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V).

Symbol	ol Parameter Conditions		74AHC125			74AHCT125			Unit
			Min	Тур	Max	Min	Тур	Max	
V_{CC}	supply voltage		2.0	5.0	5.5	4.5	5.0	5.5	V
V_{I}	input voltage		0	-	5.5	0	-	5.5	V
V_{O}	output voltage		0	-	V_{CC}	0	-	V_{CC}	V
T_{amb}	ambient temperature		-40	+25	+125	-40	+25	+125	°C
$\Delta t/\Delta V$	input transition rise	V_{CC} = 3.3 V \pm 0.3 V	-	-	100	-	-	-	ns/V
	and fall rate	V_{CC} = 5.0 V \pm 0.5 V	-	-	20	-	-	20	ns/V

9. Static characteristics

Table 6. Static characteristics

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C -		–40 °C t	o +85 °C	–40 °C t	Unit		
			Min	Тур	Max	Min	Max	Min	Max	
For type	74AHC125									
V_{IH}	HIGH-level	$V_{CC} = 2.0 \text{ V}$	1.5	-	-	1.5	-	1.5	-	V
	input voltage	$V_{CC} = 3.0 \text{ V}$	2.1	-	-	2.1	-	2.1	-	V
		$V_{CC} = 5.5 \text{ V}$	3.85	-	-	3.85	-	3.85	-	V
V_{IL}	LOW-level	$V_{CC} = 2.0 \text{ V}$	-	-	0.5	-	0.5	-	0.5	V
	input voltage	$V_{CC} = 3.0 \text{ V}$	-	-	0.9	-	0.9	-	0.9	V
		$V_{CC} = 5.5 \text{ V}$	-	-	1.65	-	1.65	-	1.65	V

Table 6. Static characteristics ...continued Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		25 °C		-40 °C	to +85 °C	–40 °C t	o +125 °C	Un
			Min	Тур	Max	Min	Max	Min	Max	
/ _{OH}	HIGH-level	$V_I = V_{IH}$ or V_{IL}							•	
	output voltage	$I_O = -50 \mu A$; $V_{CC} = 2.0 \text{ V}$	1.9	2.0	-	1.9	-	1.9	-	V
		$I_O = -50 \mu A$; $V_{CC} = 3.0 \text{ V}$	2.9	3.0	-	2.9	-	2.9	-	V
		$I_O = -50 \mu A$; $V_{CC} = 4.5 \text{ V}$	4.4	4.5	-	4.4	-	4.4	-	V
		$I_O = -4.0 \text{ mA}; V_{CC} = 3.0 \text{ V}$	2.58	-	-	2.48	-	2.40	-	V
		$I_{O} = -8.0 \text{ mA}; V_{CC} = 4.5 \text{ V}$	3.94	-	-	3.8	-	3.70	-	V
/ _{OL}	LOW-level	$V_I = V_{IH}$ or V_{IL}								
	output voltage	$I_O = 50 \mu A; V_{CC} = 2.0 V$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 50 \mu A; V_{CC} = 3.0 \text{ V}$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 50 \mu A; V_{CC} = 4.5 V$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 4.0 \text{ mA}; V_{CC} = 3.0 \text{ V}$	-	-	0.36	-	0.44	-	0.55	V
		$I_O = 8.0 \text{ mA}; V_{CC} = 4.5 \text{ V}$	-	-	0.36	-	0.44	-	0.55	V
OZ	OFF-state output current	$V_I = V_{IH} \text{ or } V_{IL};$ $V_O = V_{CC} \text{ or GND};$ $V_{CC} = 5.5 \text{ V}$	-	-	±0.25	-	±2.5	-	±10.0	μΑ
I	input leakage current	V _I = 5.5 V or GND; V _{CC} = 0 V to 5.5 V	-	-	0.1	-	1.0	-	2.0	μΔ
СС	supply current	$V_I = V_{CC}$ or GND; $I_O = 0$ A; $V_{CC} = 5.5 \text{ V}$	-	-	2.0	-	20	-	40	μA
ો	input capacitance		-	3.0	10	-	10	-	10	рF
Co	output capacitance		-	4.0	-	-	-	-	-	рF
or type	74AHCT125									
/ _{IH}	HIGH-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	2.0	-	-	2.0	-	2.0	-	V
/ _{IL}	LOW-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	-	-	8.0	-	0.8	-	0.8	V
′он	HIGH-level	$V_I = V_{IH}$ or V_{IL} ; $V_{CC} = 4.5 \text{ V}$								
	output voltage	$I_{O} = -50 \mu\text{A}$	4.4	4.5	-	4.4	-	4.4	-	V
		$I_{O} = -8.0 \text{ mA}$	3.94	-	-	3.8	-	3.70	-	V
OL.	LOW-level	$V_I = V_{IH}$ or V_{IL} ; $V_{CC} = 4.5 \text{ V}$								
	output voltage	Ι _Ο = 50 μΑ	-	0	0.1	-	0.1	-	0.1	V
		$I_0 = 8.0 \text{ mA}$	-	-	0.36	-	0.44	-	0.55	٧
OZ	OFF-state output current	per input pin; $V_I = V_{IH}$ or V_{IL} ; $V_{CC} = 5.5 \text{ V}$; $I_O = 0 \text{ A}$	-	-	±0.25	-	±2.5	-	±10.0	μA
		$V_O = V_{CC}$ or GND; other pins at V_{CC} or GND								
l	input leakage current	V _I = 5.5 V or GND; V _{CC} = 0 V to 5.5 V	-	-	0.1	-	1.0	-	2.0	μΑ
СС	supply current	$V_I = V_{CC}$ or GND; $I_O = 0$ A; $V_{CC} = 5.5 \text{ V}$	-	-	2.0	-	20	-	40	μΑ

Table 6. Static characteristics ...continued

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		25 °C		-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Тур	Max	Min	Max	Min	Max	
Δl _{CC}	additional supply current	per input pin; $V_{I} = V_{CC} - 2.1 \text{ V; } I_{O} = 0 \text{ A;}$ other pins at V_{CC} or GND; $V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	-	-	1.35	-	1.5	-	1.5	mA
C _I	input capacitance		-	3.0	10	-	10	-	10	pF
Co	output capacitance		-	4.0	-	-	-	-	-	pF

10. Dynamic characteristics

Table 7. Dynamic characteristics

GND = 0 V; For test circuit see Figure 8.

Symbol	Parameter	Conditions			25 °C		-40 °C	to +85 °C	-40 °C to +125 °C		Unit
				Min	Typ[1]	Max	Min	Max	Min	Max	
For type	74AHC125								'		
t _{pd}	propagation	nA to nY; see Figure 6	[2]								
	delay	$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$									
		C _L = 15 pF		-	4.4	8.0	1.0	9.5	1.0	11.5	ns
		$C_L = 50 pF$		-	6.2	11.5	1.0	13.0	1.0	14.5	ns
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$									
		C _L = 15 pF		-	3.0	5.5	1.0	6.5	1.0	7.0	ns
		$C_L = 50 pF$		-	4.3	7.5	1.0	8.5	1.0	9.5	ns
t _{en}	enable time	nOE to nY; see Figure 7	[2]								
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$									
		C _L = 15 pF		-	4.7	8.0	1.0	9.5	1.0	11.5	ns
		$C_L = 50 pF$		-	6.8	11.5	1.0	13.0	1.0	14.5	ns
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$									
		C _L = 15 pF		-	3.3	5.1	1.0	6.0	1.0	6.5	ns
		$C_L = 50 pF$		-	4.7	7.1	1.0	8.0	1.0	9.0	ns
t _{dis}	disable time	nOE to nY; see Figure 7	[2]								
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$									
		C _L = 15 pF		-	6.7	9.7	1.0	11.5	1.0	12.5	ns
		$C_L = 50 pF$		-	9.6	13.2	1.0	15.0	1.0	16.5	ns
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$									
		C _L = 15 pF		-	4.8	6.8	1.0	8.0	1.0	8.5	ns
		$C_L = 50 pF$		-	6.8	8.8	1.0	10.0	1.0	11.0	ns
C_{PD}	power dissipation capacitance	$C_L = 50 \text{ pF}; f_i = 1 \text{ MHz};$ $V_I = \text{GND to } V_{CC}$	[3]	-	10	-	-	-	-	-	pF

Table 7. Dynamic characteristics ...continued

GND = 0 V; For test circuit see Figure 8.

Symbol	Parameter	Conditions			25 °C		-40 °C 1	to +85 °C	-40 °C t	o +125 °C	Unit
				Min	Typ[1]	Max	Min	Max	Min	Max	
For type	74AHCT125	'							1		
t _{pd}	propagation	nA to nY; see Figure 6	[2]								
	delay	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$									
		$C_{L} = 15 pF$		-	3.0	5.5	1.0	6.5	1.0	7.0	ns
		$C_L = 50 pF$		-	4.3	7.5	1.0	8.5	1.0	9.5	ns
t _{en}	enable time	nOE to nY; see Figure 7									
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$									
		$C_{L} = 15 pF$		-	3.4	5.1	1.0	6.0	1.0	6.5	ns
		$C_L = 50 pF$		-	4.9	7.3	1.0	8.3	1.0	9.5	ns
t _{dis}	disable time	nOE to nY; see Figure 7	[2]								
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$									
		$C_{L} = 15 pF$		-	4.5	6.8	1.0	8.0	1.0	8.5	ns
		$C_L = 50 pF$		-	6.5	8.8	1.0	10.0	1.0	11.0	ns
C _{PD}	power dissipation capacitance	$C_L = 50 \text{ pF}; f_i = 1 \text{ MHz};$ $V_I = \text{GND to } V_{CC}$	[3]	-	12	-	-	-	-	-	pF

- [1] Typical values are measured at nominal supply voltage ($V_{CC} = 3.3 \text{ V}$ and $V_{CC} = 5.0 \text{ V}$).
- [2] t_{pd} is the same as t_{PLH} and t_{PHL}.

 t_{en} is the same as t_{PZL} and t_{PZH} .

 $t_{\mbox{\scriptsize dis}}$ is the same as $t_{\mbox{\scriptsize PLZ}}$ and $t_{\mbox{\scriptsize PHZ}}.$

[3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma (C_L \times V_{CC}^2 \times f_o) \text{ where:}$

 f_i = input frequency in MHz, f_o = output frequency in MHz

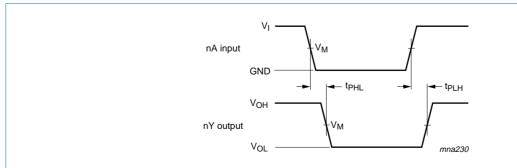
C_L = output load capacitance in pF

V_{CC} = supply voltage in Volts

N = number of inputs switching

 $\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

11. Waveforms



Measurement points are given in Table 8.

V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 6. Propagation delay input (nA) to output (nY)

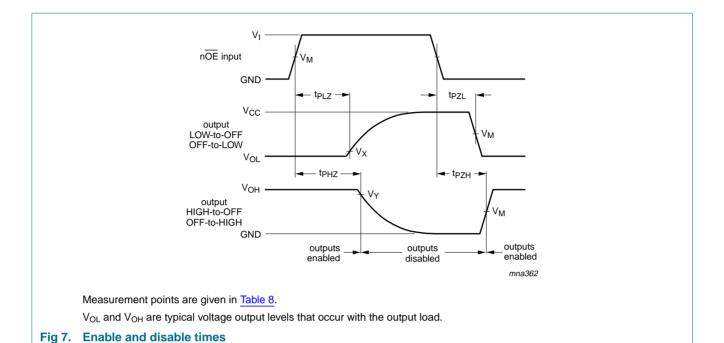
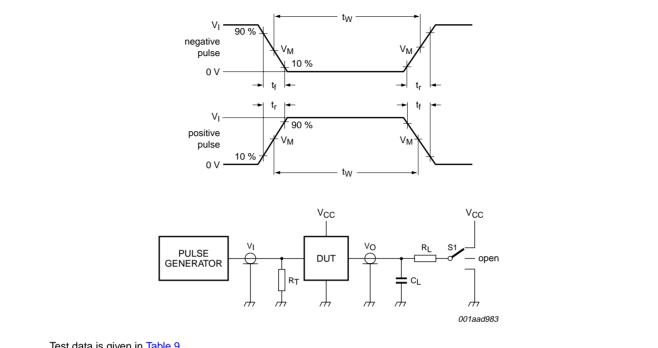


Table 8. Measurement points

Туре	Input	Output					
	V _M	V _M	V _X	V _Y			
74AHC125	0.5V _{CC}	0.5V _{CC}	V _{OL} + 0.3 V	V _{OL} – 0.3 V			
74AHCT125	1.5 V	0.5V _{CC}	V _{OL} + 0.3 V	V _{OL} – 0.3 V			

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Test data is given in Table 9.

Definitions test circuit:

 R_T = Termination resistance should be equal to output impedance Z_0 of the pulse generator.

 C_L = Load capacitance including jig and probe capacitance.

R_L = Load resistance.

S1 = Test selection switch.

Fig 8. Load circuit for switching times

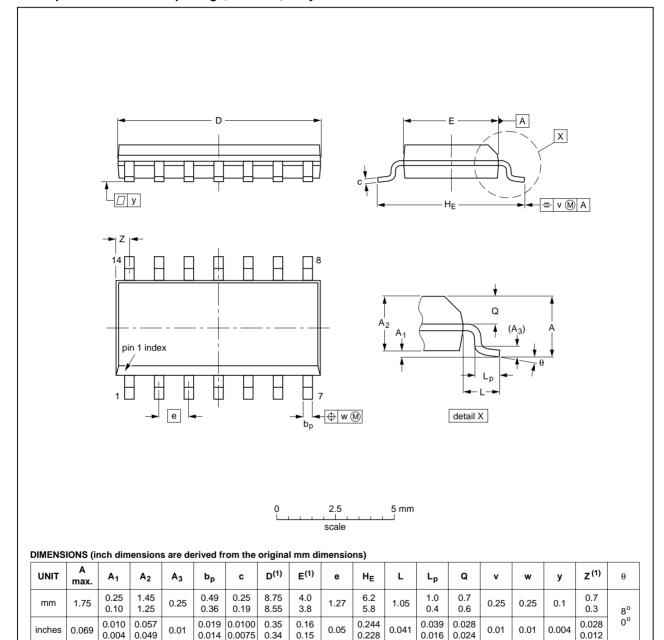
Table 9. **Test data**

Туре	Input		Load		S1 position	S1 position				
	VI	t _r , t _f	CL	R _L	t _{PHL} , t _{PLH}	t _{PZH} , t _{PHZ}	t _{PZL} , t _{PLZ}			
74AHC125	V_{CC}	≤ 3.0 ns	15 pF, 50 pF	1 kΩ	open	GND	V _{CC}			
74AHCT125	3.0 V	≤ 3.0 ns	15 pF, 50 pF	1 kΩ	open	GND	V _{CC}			

12. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



Note

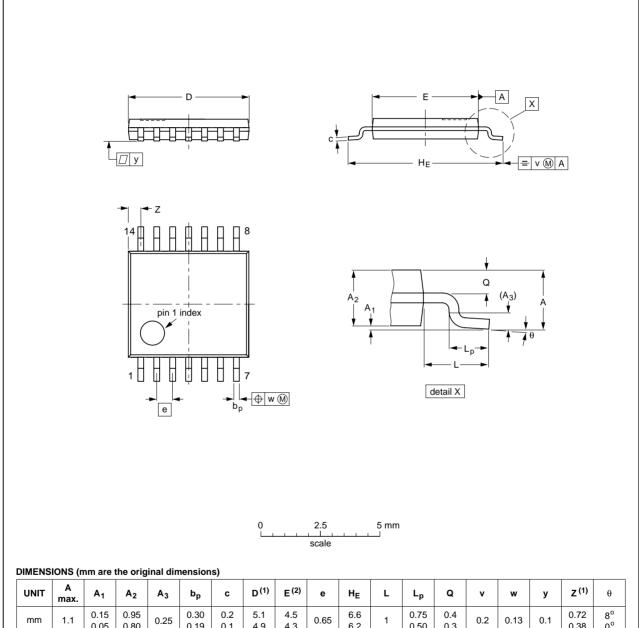
1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT108-1	076E06	MS-012				99-12-27 03-02-19

Fig 9. Package outline SOT108-1 (SO14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1



UNI	Γ A max.	A ₁	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽²⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE			REFER	EUROPEAN	ISSUE DATE		
	VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
	SOT402-1		MO-153				99-12-27 03-02-18

Fig 10. Package outline SOT402-1 (TSSOP14)

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DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm SOT762-1

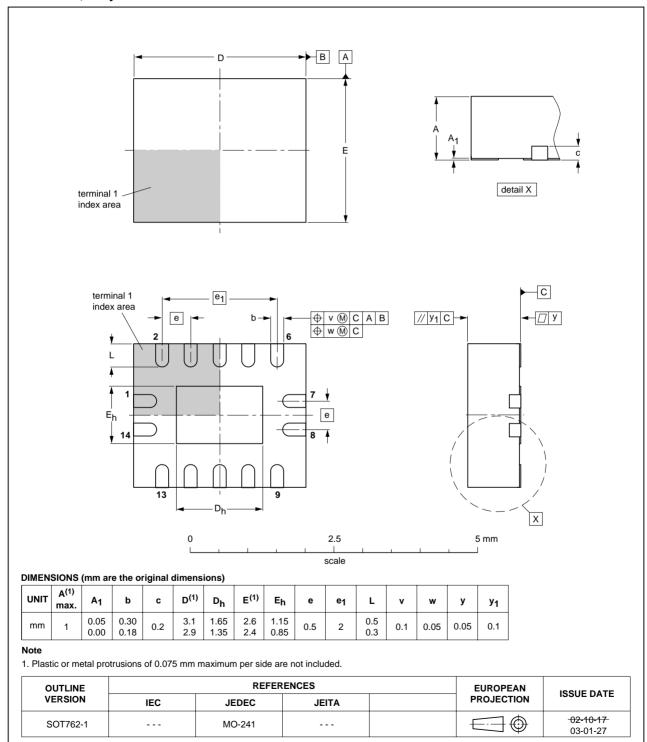


Fig 11. Package outline SOT762-1 (DHVQFN14)

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13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
LSTTL	Low-power Schottky Transistor-Transistor Logic
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
CDM	Charge-Device Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 11. Revision history

	•			
Document ID	Release date	Data sheet status	Change notice	Supersedes
74AHC_AHCT125_4	20080111	Product data sheet	-	74AHC_AHCT125_3
Modifications:	redesigned to comply v	with the new identity		
	 Legal texts 	have been adapted to the n	ew company name whe	ere appropriate.
	• Section 3: E	HVQFN14 package added		
	• Section 7: d	erating values added for DI	HVQFN14 package.	
	• Section 12:	outline drawing added for D	HVQFN14 package.	
74AHC_AHCT125_3	20060324	Product data sheet	-	74AHC_AHCT125_2
74AHC_AHCT125_2	19990927	Product specification	-	74AHC_AHCT125_N_1
74AHC_AHCT125_N_1	19990111	Product specification	-	-

15. Legal information

15.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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